

**JUN 27 2007**

S3-02P11786 - Application No.: 10/531,250  
Responsive to Notice of Non-Compliant Amdt dated: 06/19/2007  
Correction dated: 06/27/2007

**Amendments to the Claims**

**Listing of Claims:**

Claims 1-23 (canceled).

Claim 24 (new). A method for mounting a switching module, which comprises:

providing a circuit support with flat sides, a basic housing element with walls and an interior formed with guide devices, and cover element for closing the basic housing element;

inserting the circuit support into the basic housing element with the flat sides facing towards the walls of the basic housing element;

inserting a longitudinally extended pressure strip between the circuit support and the basic housing element, bracing the pressure strip with a given compression force against a flat side of the circuit support, and guiding the pressure strip with the guide devices in the interior of the basic housing element; and

closing the basic housing element with the cover elements.

Claim 25 (new). The method according to claim 24, wherein the pressure strip is a tension spring, and the method comprises inserting the circuit support in a tensed state of the spring and subsequently releasing the spring to fix the circuit support in the basic housing element.

Claim 26 (new). The method according to claim 24, wherein the pressure strip is a compression spring and the method comprises fixing the circuit support by subjecting the spring to a compression pressure.

Claim 27 (new). The method according to claim 26, which comprises applying the compression pressure by way of the cover elements of the basic housing

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element.

Claim 28 (new). The method according to claim 24, which comprises guiding the pressure strip inside the basic housing element by an encapsulated guide groove.

Claim 29 (new). The method according to claim 24, which comprises guiding the circuit support by guide elements during insertion into the basic housing element.

Claim 30 (new). The method according to claim 29, which comprises fitting the circuit support with components on both sides before insertion into the basic housing element.

Claim 31 (new). The method according to claim 24, which comprises fixing a cover element to the circuit support before insertion of the circuit support into the basic housing element.

Claim 32 (new). The method according to claim 31, which comprises connecting contact means configured on the cover element to the circuit support before insertion of the circuit support into the basic housing element.

Claim 33 (new). The method according to claim 24, which comprises inserting the pressure strip into the basic housing element together with the circuit support.

Claim 34 (new). The method according to claim 24, providing a cover element with the pressure strip attached to an opening in the basic housing element.

Claim 35 (new). The method according to claim 24, which comprises adapting the pressure strip to a length of the basic housing element by breaking at predetermined breaking points before insertion into the basic housing element.

Claim 36 (new). The method according to claim 24, which comprises holding the pressure strip in a form lock in a recess in an opposite cover element.

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Claim 37 (new). The method according to claim 36, wherein the pressure strip is configured with a saw-tooth profile and the pressure strip is held positively in latch points on the recess.

Claim 38 (new). The method according to claim 36, which comprises clamping the basic housing element between mutually opposite cover elements.

Claim 39 (new). The method according to claim 24, which comprises fixing a cover element to the circuit support by way of clamping devices during an attachment of the cover element to an opening in the basic housing element.

Claim 40 (new). The method according to claim 24, which comprises sealing openings formed on mutually opposite sides of the basic housing element by way of mutually identical seals.

Claim 41 (new). A switching module with an electronic component disposed inside a housing, wherein the switching module is produced with the method according to claim 24.